

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-24. (Canceled)

25. (Previously Presented) A method for fabricating a semiconductor circuit module, the method comprising:

providing circuit devices, each having a contact area on a front side thereof;
applying a patterned connection layer to a transfer substrate;
applying the front sides of the circuit devices to the patterned connection layer;
curing the patterned connection layer after applying said circuit devices;
applying a filler between the circuit devices;
removing the transfer substrate; and
applying an electrical connection device to connect the circuit devices.

26. (Previously Presented) The method according to claim 25, further comprising applying a protection layer at least partially covering the electrical connection device.

27. (Previously Presented) The method according to claim 26, further comprising providing a second electrical connection device in a region not covered by the protection layer.

28. (Previously Presented) The method according to claim 25, wherein applying the patterned connection layer comprises printing the patterned connection layer on the transfer substrate.

29. (Previously Presented) The method according to claim 25, further comprising arranging said circuit devices on said patterned connection layer, such that the contact areas of said circuit devices are not located on said patterned connection layer.

30. (Canceled)

31. (Previously Presented) The method according to claim 25, further comprising providing an encapsulation layer on backsides of said circuit devices.

32. (Previously Presented) The method according to claim 25, wherein applying the filler comprises selecting a process from the group consisting of casting and printing.

33. (Previously Presented) The method according to claim 31, wherein applying the encapsulation layer comprises selecting a process from the group consisting of casting and printing.

34. (Previously Presented) The method according to claim 25, further comprising curing said filler before removing said transfer substrate.

35. (Previously Presented) The method according to claim 31, further comprising curing said encapsulation layer before removing said transfer substrate.

36-52. (Canceled)